

CLEANING LIQUID FOR POLYIMIDE PRECURSOR COMPOSITION AND SURFACE PROTECTIVE FILM USING THE SAME OR METHOD FOR FORMING INTERLAMINAR INSULATING FILM

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Abstract of JP2001011494

PROBLEM TO BE SOLVED: To provide a high safety cleaning liquid for polyimide precursor compositions which can easily remove a polyimide precursor composition entered into the back of a semiconductor substrate and the like in spinning coating the polyimide precursor composition on the surface of the semiconductor substrate and the like and, at the same time, bring about an effect of reducing the height of a build-up which is composed of the polyimide precursor composition and caused at the end portions of the surface of a substrate upon spinning coating.

SOLUTION: A cleaning liquid for polyimide precursor compositions comprising a sulfur-containing organic solvent or a sulfur-containing organic solvent and a poor solvent for the polyimide precursor compositions is used. Preferably, dimethyl sulfoxide is used as the sulfur-containing organic solvent. Preferably, the cleaning liquid for polyimide precursor compositions having a solidifying point of 18.5 deg.C to -80 deg.C is used.

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